

**Product Texts**

LNP THERMOCOMP OF006 compound is based on linear Polyphenylene Sulfide (PPS) resin containing 30% glass fiber.

UL Yellow Card Link [E121562-101283821](https://www.ul.com/yellowcard/E121562-101283821)

<b>Processing/Physical Characteristics</b>	<b>Value</b>	<b>Unit</b>	<b>Test Standard</b>
<b>ASTM Data</b>			
Mold Shrinkage, MD	0.2	mm/mm	ASTM D 955
Mold Shrinkage, TD	0.8	mm/mm	ASTM D 955
<b>Mechanical properties</b>			
<b>ISO Data</b>			
Tensile Modulus	12000	MPa	ISO 527
Stress at break	126	MPa	ISO 527
Strain at break	1.3	%	ISO 527
Flexural modulus	10500	MPa	ISO 178
Izod impact strength, +23°C, 4mm	24	kJ/m <sup>2</sup>	ISO 180/1U
Izod notched impact strength, +23°C, 4mm	5	kJ/m <sup>2</sup>	ISO 180/1A
<b>ASTM Data</b>			
Tensile Modulus	12100	MPa	ASTM D 638
Tensile Strength at Break	132	MPa	ASTM D 638
Elongation at Break	1.4	%	ASTM D 638
Flexural Modulus	10000	MPa	ASTM D 790
Izod Impact notched, 1/8 in	58	J/m	ASTM D 256
Izod Impact unnotched, 1/8 in	391	J/m	ASTM D 256
<b>Thermal properties</b>			
<b>ISO Data</b>			
Temp. of deflection under load, 1.80 MPa	258	°C	ISO 75-1/-2
Temp. of deflection under load, 0.45 MPa	275	°C	ISO 75-1/-2
Burning behav. at thickness h	V-0	class	IEC 60695-11-10
Thickness tested	0.5	mm	-
Burning behav. 5V at thickness h	5VA	class	IEC 60695-11-20
Thickness tested	1.5	mm	-
<b>ASTM Data</b>			
Coefficient of Thermal Expansion, MD	22	E-6/K	ASTM D 696
Coefficient of Thermal Expansion, TD	45	E-6/K	ASTM D 696
DTUL @ 66 psi	276	°C	ASTM D 648
DTUL @ 264 psi	261	°C	ASTM D 648
<b>Other properties</b>			
Humidity absorption	0.06	%	Sim. to ISO 62
Density	1570	kg/m <sup>3</sup>	ISO 1183
Water Absorption, 24hr	0.02	%	ASTM D 570
Density	1570	kg/m <sup>3</sup>	ASTM D 792
<b>Processing Recommendation Injection Molding</b>			
Pre-drying - Temperature	120 - 150	°C	-
Pre-drying - Time	4	h	-
Melt temperature	315 - 320	°C	-
Mold temperature	140 - 165	°C	-
Zone 1	305 - 315	°C	-
Zone 2	320 - 330	°C	-
Zone 3	330 - 345	°C	-
Screw speed	30 - 60	rpm	-
Back pressure	0.2 - 0.3	MPa	-

**Characteristics**

**Processing**

Injection Molding

**Regional Availability**

North America, Europe, Asia Pacific